



NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE :  
 W/B NO.15,16,45,46,75,76,105,106-----200mOHMS MAX.  
 W/B NO.1,31,61,91-----500mOHMS MAX.  
 THE OTHERS-----800mOHMS MAX.

MODIFICATION					NAME 121 PIN GRID ARRAY PACKAGE			TOLERANCE ±.005		DRAWN   CHECKED   APPROVED		DATE JUL16/95	
REDRAWN					SCALE 5/1			MATERIAL AS INDICATED		K.I		T.A	
CHANGED					DATE DRAWN   CHECKED   APPROVED			KYOCERA CORPORATION KYOTO JAPAN		DRAWN BY NO. KD-85019-A		SHEET 1/3	





WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	C3	27	M1	53	N10	79	F12	105	B7
2	B2	28	K3	54	L9	80	F11	106	C7
3	B1	29	L2	55	M10	81	E13	107	A7
4	D3	30	N1	56	N11	82	E12	108	A6
5	C2	31	L3	57	N12	83	D13	109	B6
6	C1	32	M2	58	L10	84	E11	110	C6
7	D2	33	N2	59	M11	85	D12	111	A5
8	E3	34	L4	60	N13	86	C13	112	B5
9	D1	35	M3	61	L11	87	B13	113	A4
10	E2	36	N3	62	M12	88	D11	114	C5
11	E1	37	M4	63	M13	89	C12	115	B4
12	F3	38	L5	64	K11	90	A13	116	A3
13	F2	39	N4	65	L12	91	C11	117	A2
14	F1	40	M5	66	L13	92	B12	118	C4
15	G2	41	N5	67	K12	93	A12	119	B3
16	G3	42	L6	68	J11	94	C10	120	A1
17	G1	43	M6	69	K13	95	B11		
18	H1	44	N6	70	J12	96	A11		
19	H2	45	M7	71	J13	97	B10		
20	H3	46	L7	72	H11	98	C9		
21	J1	47	N7	73	H12	99	A10		
22	J2	48	N8	74	H13	100	B9		
23	K1	49	M8	75	G12	101	A9		
24	J3	50	L8	76	G11	102	C8		
25	K2	51	N9	77	G13	103	B8		
26	L1	52	M9	78	F13	104	A8		

  

S/R	NC
D/A	NC
EXTRA PIN (D4)	NC

MODIFICATION					NAME 121 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN K.J.	CHECKED T.A.	APPROVED	DATE JAN.18.'05
	△ REDRAWN				SCALE X	MATERIAL				
		CHANGED	DATE	M.K.A.	A.F.	M.K.	DRAWING NO. KD-85019-A		SHEET 3/3	

